

Abstract

An electronic device (1) has a base plate (2) and an electronics housing (3) connected thereto, with a bonding contact terminal (5). The latter is supported relative to the base plate (2) via
5 a supporting body (6) in such a manner that the supporting body (6) exerts a pre-stressing force onto the bonding contact terminal (5). Due to this support of the bonding contact terminal (5), its position is well defined during the bonding procedure. A secure bond is the result.